Surface Mount Green Chip LED - 0805

multicomp PRO

RoHS

Compliant



Features

- 2mm × 1.25mm SMT LED, 0.7mm Thickness.
- · Wide Viewing Angle.
- · Ideal For Backlight And Indicator.
- · Various Colours and Lens Types Available.

Applications

- Automotive: Backlighting in dashboard and switch.
- · Telecommunication: Indicator and Backlighting in telephone and fax.
- · Flat Backlight for LCD switch and symbol.

Device Selection Guide

Part No.	Chip		Lens Colour
MP005923	Material	Emitted Colour	Water Clear
	(InGaN)	Green	vvatei Cleai

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	Po	100	mW	
Forward Current	lF	25	mA	
Peak Forward Current*1	IFP	100	mA	
Reverse Voltage	VR	5	V	
Operating Temperature	Topr	-40°C To +85°C		
Storage Temperature	Tstg	-40°C To +85°C		

Notes:

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Тур.	Max	Unit	Test Conditions
Forward Voltage	VF	2.6	_	3.6	V	IF=20mA
Reverse Current	lr	_	_	10	μA	VR=5V
Dominate Wavelength	λ D	518	_	530	nm	IF=20mA
Luminous Intensity	lv	845	_	1800	mcd	IF=20mA
Viewing Angle	201/2	_	120	_	Deg.	IF=20mA

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or chromaticity), the typical accuracy of the sorting process is as follows:

wavelength: ±1nm
Luminous Intensity: ±15%
Forward Voltage: ±0.1V

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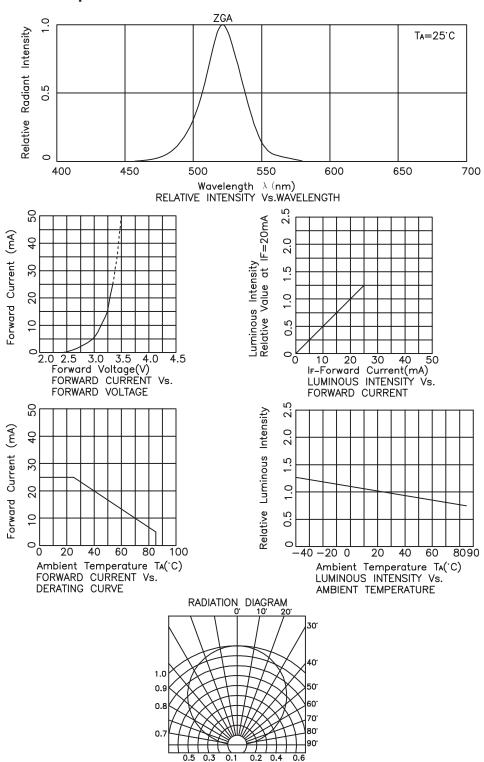


^{*1:} Pulse width≤0.1ms, Duty cycle≤1/10

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Typical Electrical/Optical Characteristics Curves



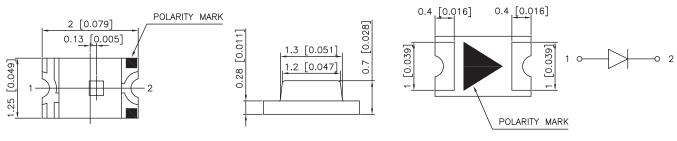
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Diagram

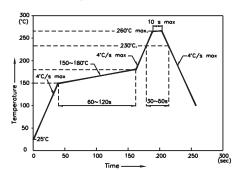


Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.15 unless otherwise noted.
- 3. Specifications are subject to change without notice.

Soldering Profile

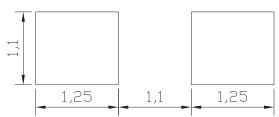
Reflow Soldering Profile For Lead-free SMT Process.



Notes

- 1. We recommend the reflow temperature 245°C. (±5°C) The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern



Part Number Table

Description	Part Number
SMD Chip LED, 0805, Green, 1800mcd, 120°	MP005923

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